

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound 29988- POM-K, M-GNR, 03-002 POM copolymer easy flowing injection molding type with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. The products are in compliance with EU regulations (EC) No 1935/2004, (EC) No 2023/2006 and (EU) 10/2011, USA FDA 21 CFR Titles 174 - 199, and Chinese food contact regulations GB4806.1, GB31603 and GB9685.

Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances.

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Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	13 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile modulus	2700	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	10	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Charpy notched impact strength, 23°C		kJ/m ²	ISO 179/1eA
Poisson's ratio	0.38 ^[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3

Physical/Other properties

5	4440 1 / 3	100 4400
Density	1410 kg/m³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa

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Characteristics

Additives Release agent

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Melt temperature 190-210 °C Mould temperature 80-120 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Film extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

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Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C Annealing time 10 min/mm thickness

Other extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C Annealing time 10 min/mm thickness

Sheet extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

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Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C Annealing time 10 min/mm thickness

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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